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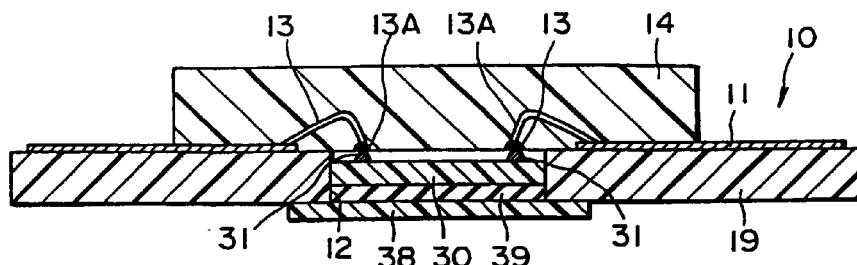
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(54) **Wiring circuit board for mounting of semiconductor chip and method for the preparation thereof**

(57) Proposed is a novel wiring circuit board for mounting of a semiconductor chip suitable for free mounting and demounting thereof. The wiring circuit board (10) comprises: an insulating base plate (19) provided with electrodes (11) on one surface and having an opening (12) for insertion of the semiconductor chip; bonding wires (13) each connected to one of the electrodes at one end, with the other end appearing in the opening at a position just to come into contact with the electrode of a semiconductor chip (30) inserted into the opening; and a resinous encapsulating layer (14) cover-

ing the opening and embedding the bonding wires. A method for the preparation of this wiring circuit board is also disclosed in which accurate positioning of the ends of the bonding wires appearing in the opening of the base plate is accomplished by using a dummy chip (20) provided with etching-resistant false electrodes and inserted into the opening followed by subsequent removal by etching after completion of the bonding work of the bonding wires.

FIG. 2





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Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	
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			TECHNICAL FIELDS SEARCHED (Int.Cl.6)
			H01L
The present search report has been drawn up for all claims			
Place of search THE HAGUE	Date of completion of the search 8 December 1998	Examiner De Raeve, R	
CATEGORY OF CITED DOCUMENTS		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document	
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**ANNEX TO THE EUROPEAN SEARCH REPORT
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